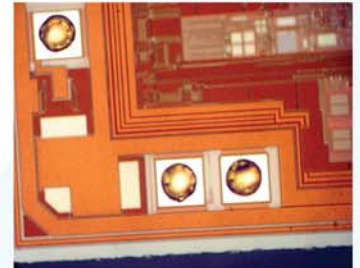


## Die Reclamation With or Without Die Reassembly

### What is Die Reclamation?

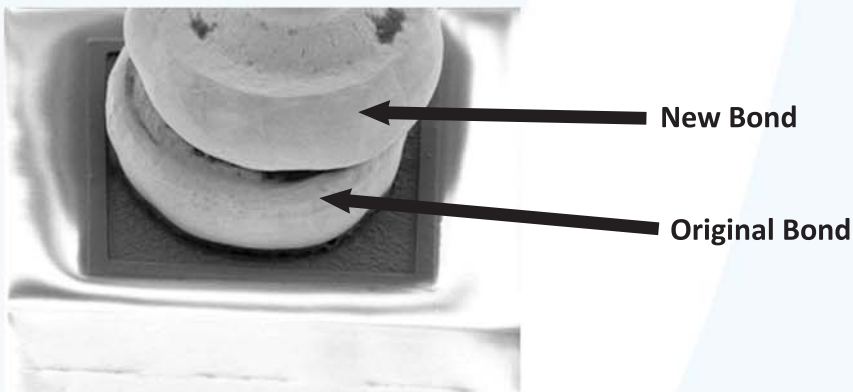
Die Reclamation is an advanced, non-destructive, die extraction technique that allows us to remove a die from any semiconductor package, making that die available in bare die form to be repackaged in any other available package, or be used in bare die form.



Clean uncontaminated surface  
ready for re-bond

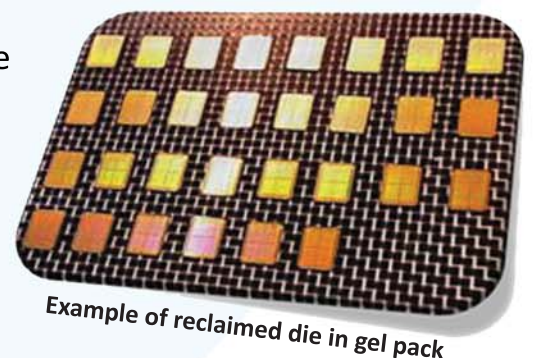
### Die Reassembly

Original gold wires are removed at the top of the original bonds. A clean, uncontaminated gold surface is used for the new, high-adhesion wire connection, or compound bond. The new gold bond is made to the original, pristine bond.



### Quality and Reliability

After die removal and subsequent reassembly, the electrical performance in the new package is carefully measured to ensure identical electrical performance when compared to that of the die in its original package. We suggest that any prospective customer first try an engineering sample of 10 to 20 units. Force can provide these samples at a very reasonable price. Force wants to earn our customer's trust through empirical data that proves that our process is highly reliable and is also the lowest cost solution available.



Example of reclaimed die in gel pack

Please contact [sales@forcetechnologies.co.uk](mailto:sales@forcetechnologies.co.uk) for further information on die reclamation or download the presentation at [www.forcetechnologies.co.uk/downloads](http://www.forcetechnologies.co.uk/downloads)